

ADAM TECH

ADAM TECHNOLOGIES INC.

INTRODUCTION:

Adam Tech HPH Series Half Pitch Pin Headers are designed for applications where space and weight are key factors. They provide a fast, simple one-step installation of multiple posts to PC boards. Both single and dual row types are available. Custom pin lengths are available to suit specific applications.

FEATURES:

- Half pitch .050" centerline increases board density
- Single and dual row types
- Breakaway style insulator for added versatility
- Molded in standoffs enable easy cleaning

MATING OPTIONS:

Mates with Adam Tech HRS and HFCS Socket Series and all other industry standard compatible connectors

SPECIFICATIONS:

Material:

Insulator: Polybutylene Terephthalate (PBT), glass reinforced thermoplastic, rated UL 94V-0

Contacts: Phosphor Bronze

Plating:

U = 5 μ m gold nom. (optional 30 μ m) to MIL-G-45204, Type II, Grade C over 50 μ m nickel underplate to QQ-N-290, Class 2, Grade C

SG = 5 μ m gold nom. (optional 30 μ m) on mating length to MIL-G-45204, Type II, Grade C, 100 μ m tin-lead to MIL-P-81728 on solder-tails

T = 100 μ m tin-lead to MIL-P-81728, Type 1 with 50 μ m copper underplate to MIL-C-14550

Electrical:

Operation voltage: 250 VAC max

Current rating: .5 Amp max

Contact resistance: 20 m Ω max

Insulation resistance: 1000 M Ω min @ 1000 VDC between adjacent contacts (75° F and 50% R.H.)

Dielectric withstanding voltage: 1000 VAC min rms (sea level)

Mechanical:

Pin push out force: 4 lbs. min

Soldering process: Wave, Vapor-phase or IR Reflow

Environmental: Operating temperature: -65°C to +125°C

PACKAGING:

Anti-static plastic bags

APPROVALS AND CERTIFICATIONS:

Recognized under the component program

of Underwriters Laboratories, Inc. No. E167232

Certified by Canadian Standards Association No. LR75112



Hi-TEMP
OPTION

OPTIONS:

Add as suffix to basic part number

15 = 15 μ m gold plating

30 = 30 μ m gold plating

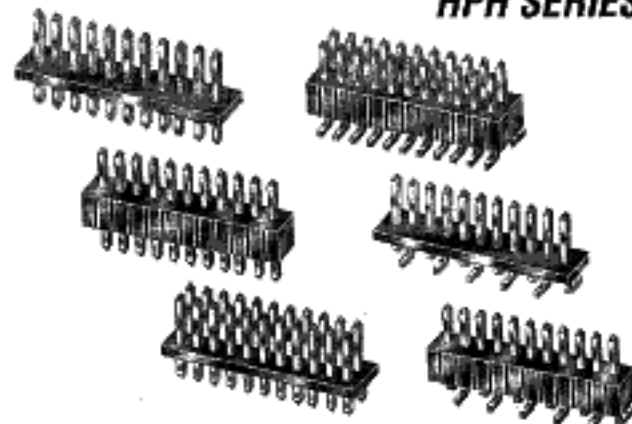
SMT = Surface mount leads

HT = Hi-Temp insulator for IR reflow or Vapor Phase soldering process

.050" PIN HEADERS

.050" [1.27] CENTERLINE

HPH SERIES



ORDERING INFORMATION

HPH2 B 100 SG A

SERIES

INDICATOR

HPH1 = .050" Single row pin header

HPH2 = .050" Dual row pin header

INSULATOR SIZE

A = 1 mm insulator thickness single or dual row (dual row .050"x.050")

B = .100" insulator thickness single or dual row (dual row .050"x.100")

POSITIONS

1 thru 32 (single row)
4 thru 100 (dual row)

MATING/ SOLDER-TAIL LENGTH

A = Standard length
B = Special length, customer specified, defined as tail length/total length

PLATING

SG = Selective gold plating in contact area
Tin-Lead plating on solder tails

U = Gold Plated

T = Tin Plated

ORDERING INFORMATION

DHPH 2 50 SG .XXX"/.XXX"/.XXX"
(C DIM) (D DIM) (E DIM)

SERIES

INDICATOR

DHPH = Dual insulator .050" centerline

SPECIFIED IN INCHES
AS: C Dim./D Dim./E Dim.
(replace D Dim. with SMT for surface mount option)

PLATING

SG = Selective gold plating in contact area and Tin-Lead plating on solder tails

NO. OF ROWS

1 = Single row
2 = Dual row .050"x.100"

POSITIONS

1 thru 32 (single row)
4 thru 100 (dual row)

<p>PC Board Layout</p>		<p>HPH1-A</p>
<p>PC Board Layout</p>		<p>HPH1-B</p>
<p>PC Board Layout</p>		<p>HPH2-A</p>
<p>PC Board Layout</p>		<p>HPH2-B</p>
<p>PC Board Layout</p>		<p>HPH1-A-SMT</p>
<p>PC Board Layout</p>		<p>HPH1-B-SMT</p>

<p>Solder Pad Layout</p>			<p>HPH2-A-SMT</p>
<p>Solder Pad Layout</p>			<p>HPH2-B-SMT</p>
<p>PC Board Layout</p>			<p>HPDH-1</p>
<p>PC Board Layout</p>			<p>HPDH-2</p>
<p>Solder Pad Layout</p>			<p>HPDH-1-SMT</p>
<p>Solder Pad Layout</p>			<p>HPDH-2-SMT</p>